



Development of Silicon Detectors for Particle and Astroparticle Physics Experiments

MPI Halbleiterlabor

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der Max-Planck-
Institute
für Physik und
extraterrestrisch
Physik



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Munich
13.12.2004



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Complete design and manufacturing chain

- » Facilities for Layout and Simulation of Semiconductor Devices
- » Production of Silicon Detectors
- » Mounting and Tests

- » Special Features:
 - » Processing of ultra-pure silicon wafers (10^{12} impurities/cm³)
 - » Double sided wafer processing
 - » Wafer scale detectors (up to 50 cm² area)



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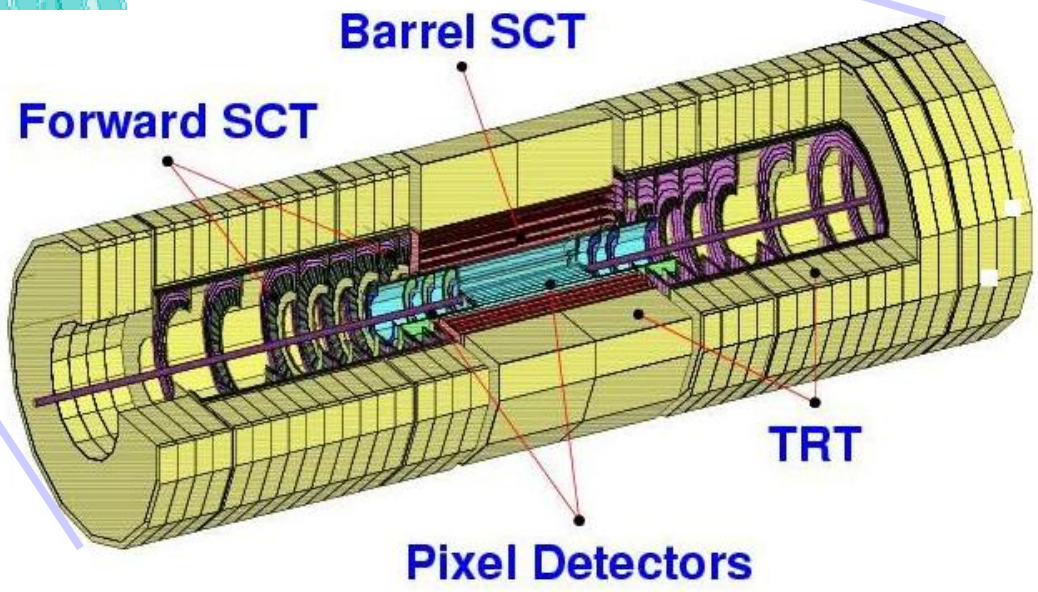
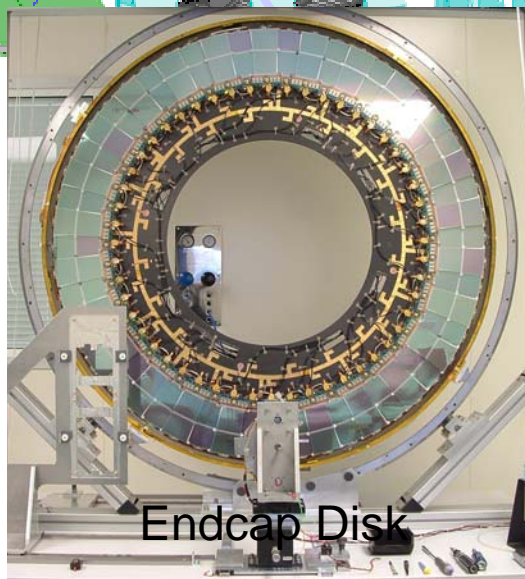
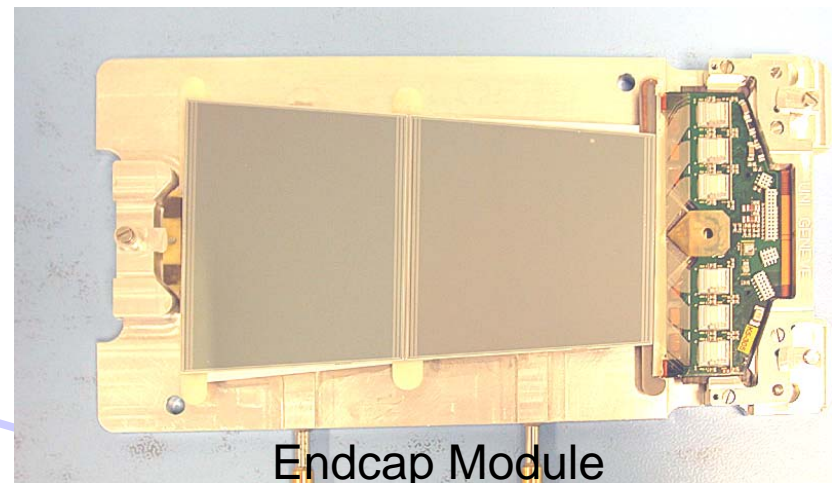
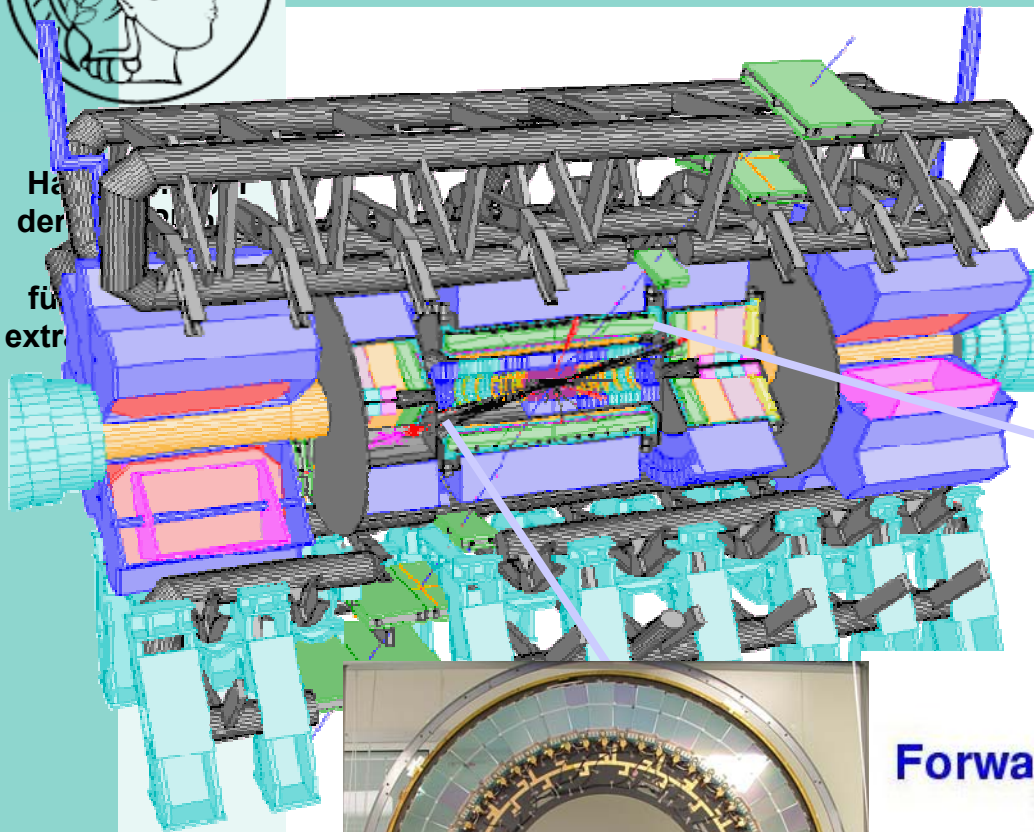
Range of Devices

| Device | Project (WHI, MPE) |
|--|---|
| Silicon Strip Detectors, passive Pixel Detectors design and prototyping production in industry quality control | ATLAS |
| pn-CCD for imaging X-Ray (and optical) detection frame store CCDs | XMM/Newton ROSITA/DUO CAST |
| Silicon-Drift-Detectors X-ray spectrometers many design derivatives: arrays integrated amplification (DEPFET) gated diodes | Siddharta DRAGO FELIX Muon Cooling |
| Active Pixel Detectors (DEPFET) for X-ray imaging and tracking detectors | XEUS ILC (TESLA) |
| Silicon Photomultipliers (R&D project) single photon detection | MAGIC, EUSO |



Silicon Strip Detectors for ATLAS SCT

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Silicon Stripdetector: ATLAS SCT

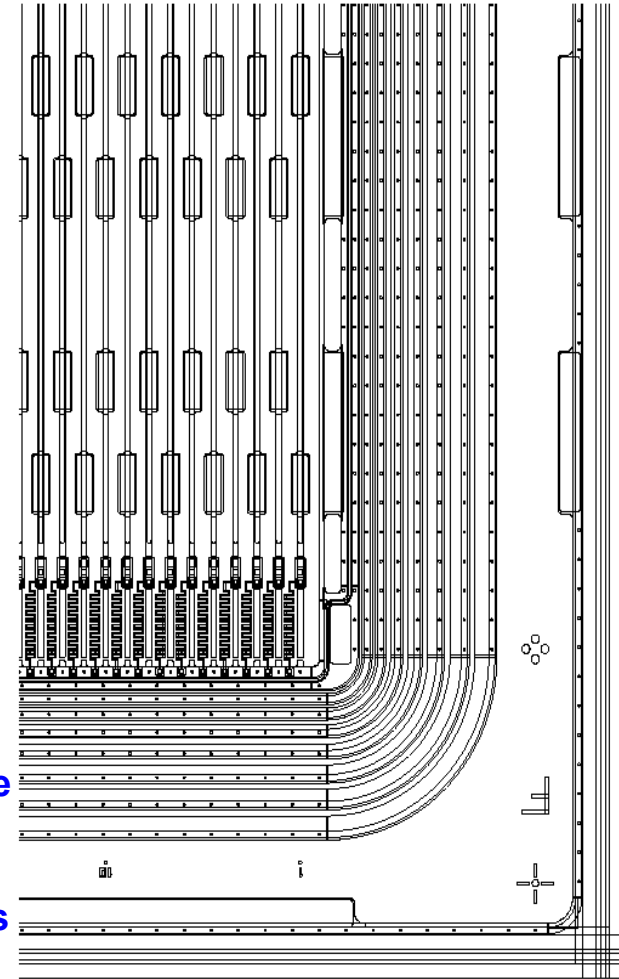
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- » Radiation tolerant up to 3×10^{14} p/cm²
- » p-on-n single sided detectors
- » 285 micron 2-8 kOhm
- » 4" substrate
- » Barrel: 64x64 mm²
- » Forward: wedge shaped (5 shapes)
- » 768 readout strips with ca 80 μ m pitch
- » No intermediate strips
- » AC coupled strips
- » Polysilicon or implanted bias resistors
- » Multiguarding structure to ensure stability up to 500 V
- » Ca. 20000 needed
- » 3100 produced CIS
- » competed, however, some problems with properties of passivation layers:

High resistivity of passivation layer leads to:

**Early breakdown (<450V) if operated in N₂ atmosphere
(10%-20% of detectors affected)**

**Noise bumps due to strips shorted by surface charges
Cured by treatment with ionized air**

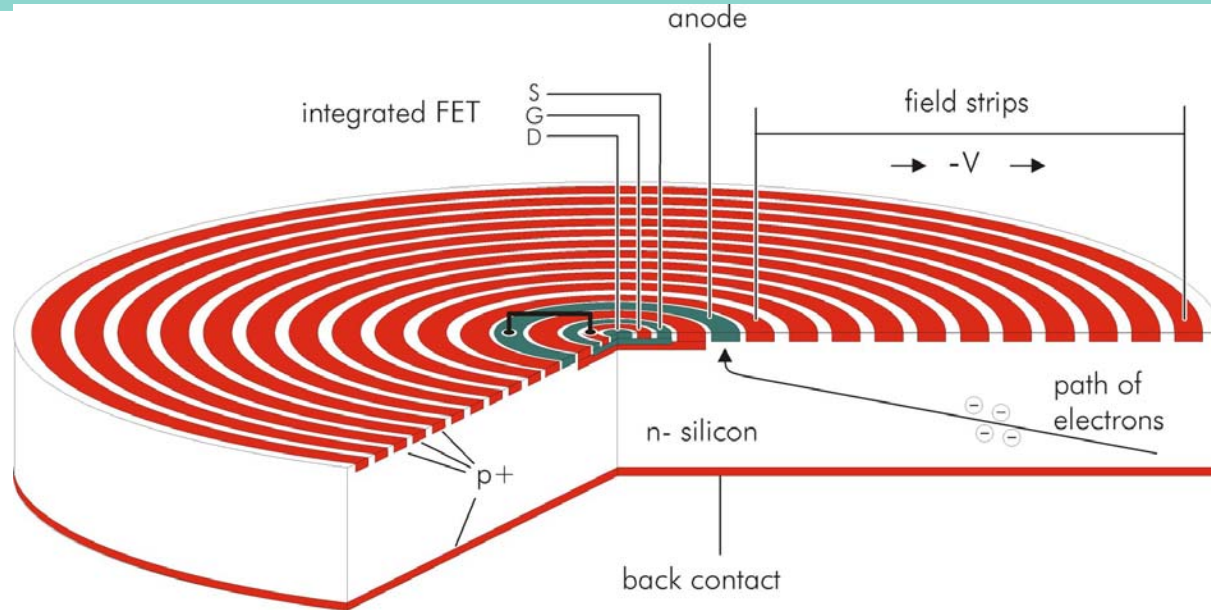


Future: detectors for Super-LHC ???



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Silicon Drift Detectors



Large detection area

Low capacitance => Low noise

Integrated Transistor for first amplification

Can be produced in many shapes

Many other detectors based on this principle

Projects: SIDDHARTA (Kaonic Atoms); Muon Cooling



Example: Mars Rover

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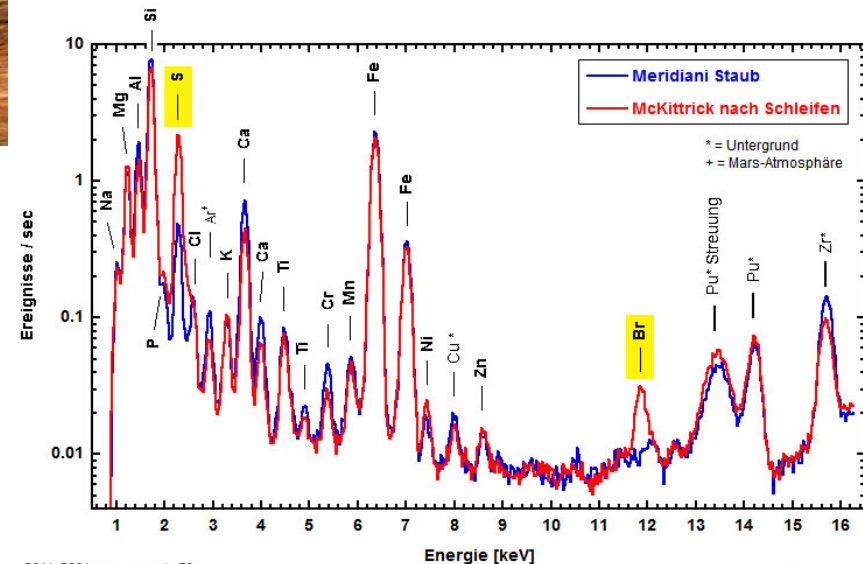
APXS

Silicon Drift Detectors for APXS X-ray fluorescence spectrometer for MPI für Kosmochemie, Mainz mission profile

- 2 independent mobile landers
“Spirit” & “Opportunity”
- arrived 04./25.01.04



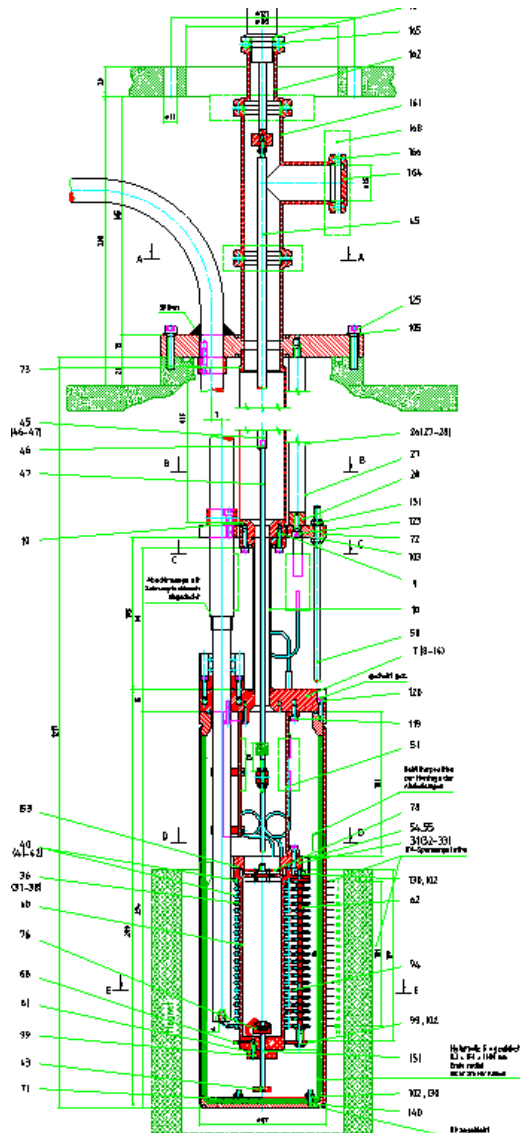
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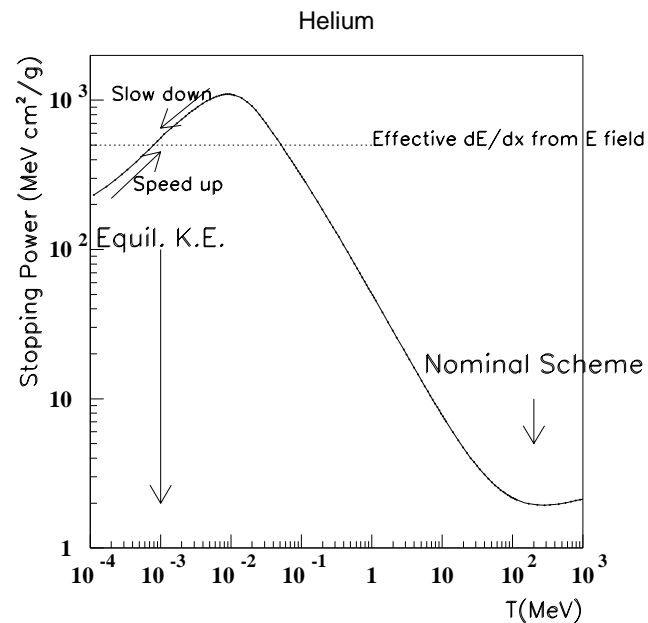
Muon Collider: Frictional Cooling Experiment

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Muon Collider:

- No synchrotron problem – better than electron
- Point particle – better than proton
- But, $\tau = 2.2 \cdot 10^{-6}$ s, so
- need μ production, cooling, acceleration, within very short time !! We focus on cooling.



$\mu^- + \text{He} \rightarrow \text{He}_\mu + e + \gamma$'s
Transition $n=2 \rightarrow n=1$
releases few KeV x-ray

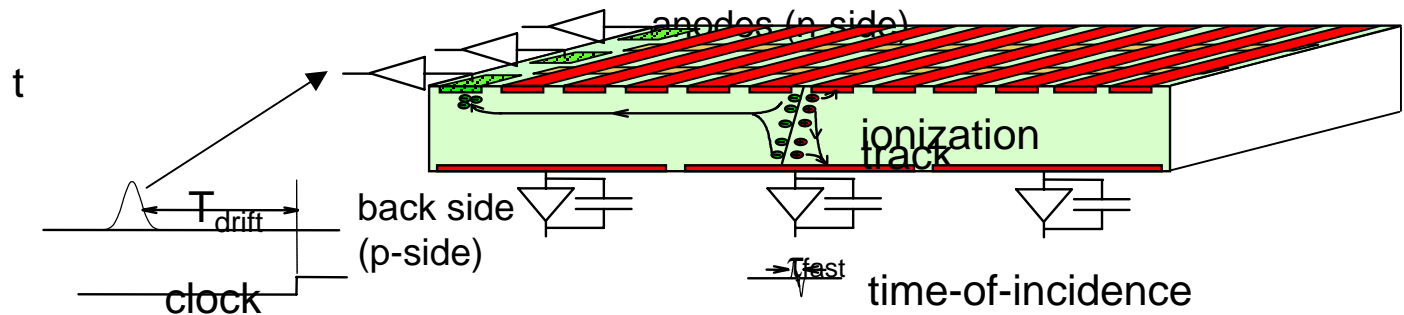
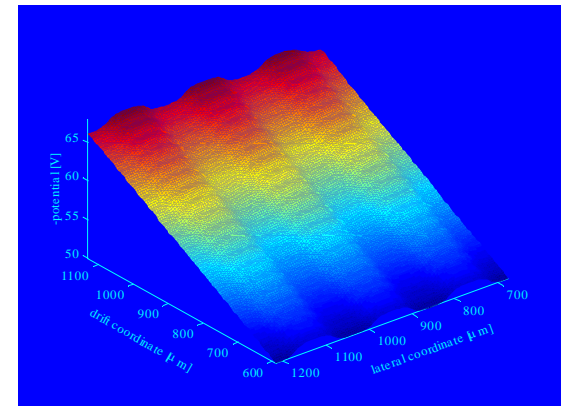
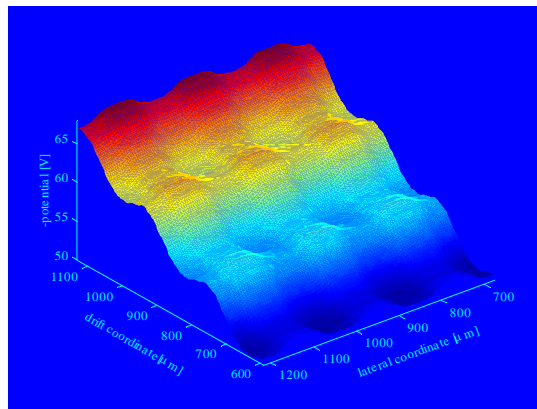
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Gated Drift Diode

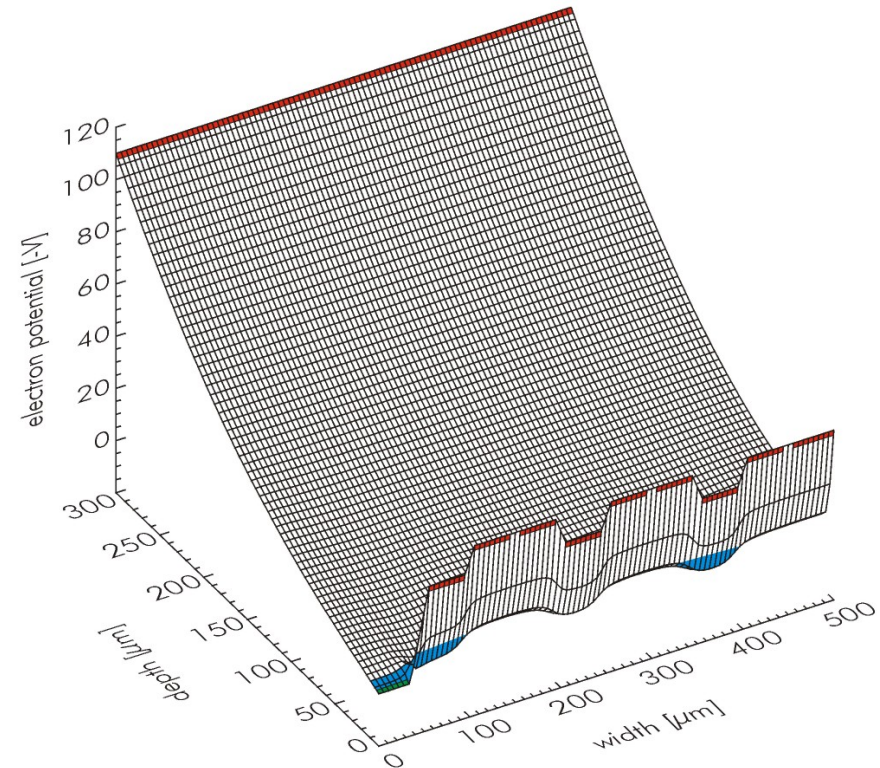
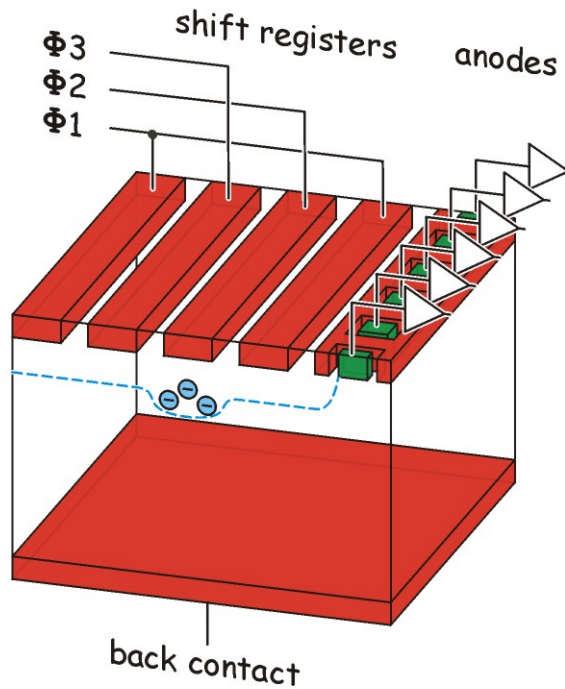
In drift diodes: t_0 information is missing: no spatial resolution.
Modulation of drift fields allows to store charge temporarily.
Drift starts if potential walls are removed.
Back side contacts can serve as trigger.

Application: Medical Imaging (DRAGO, in production)





Pn-CCDs



Like in CMOS CCDs (digital cameras) the charge is stored between potential walls and shifted by periodically modifying them
Unlike in CMOS CCDs the complete bulk is depleted and the CCD is sensitive to X-rays
Disadvantage: out of time events



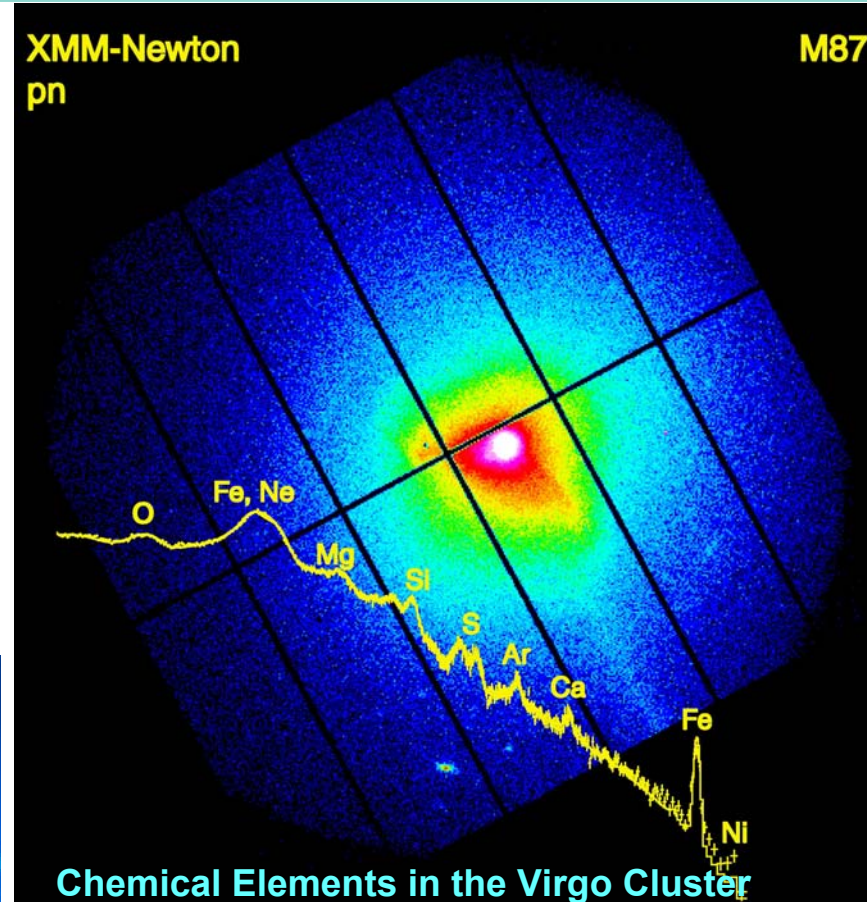
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Application in XMM/Newton

Astronomy:

X-ray CCDs (XMM-Newton):
in orbit since Dec 1999
taking data
operation support and
surveillance

World's largest X-ray CCD
Flawless operation since 5
years





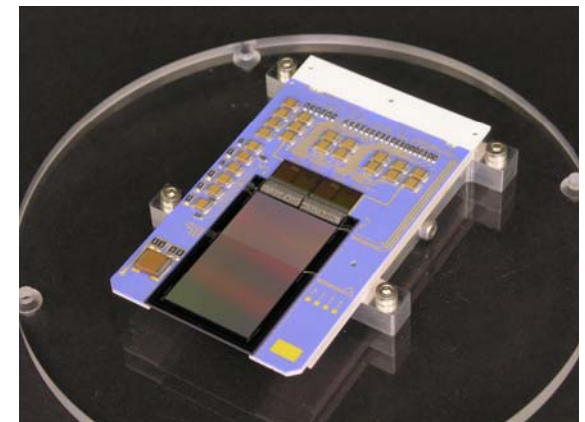
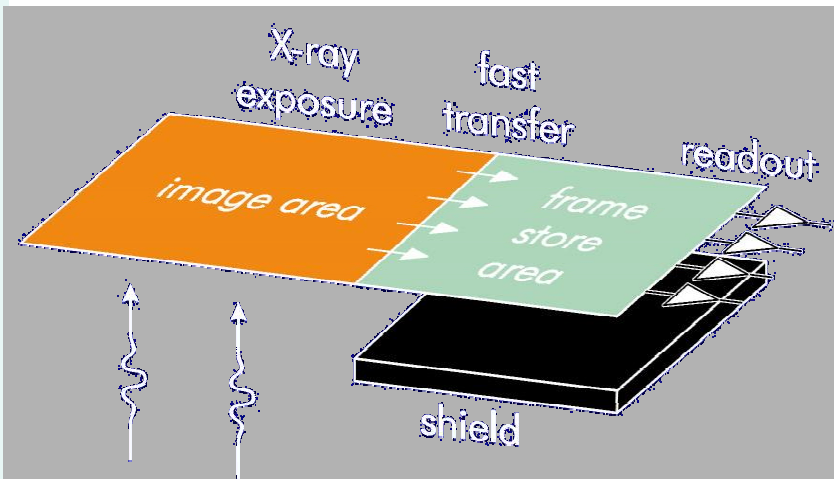
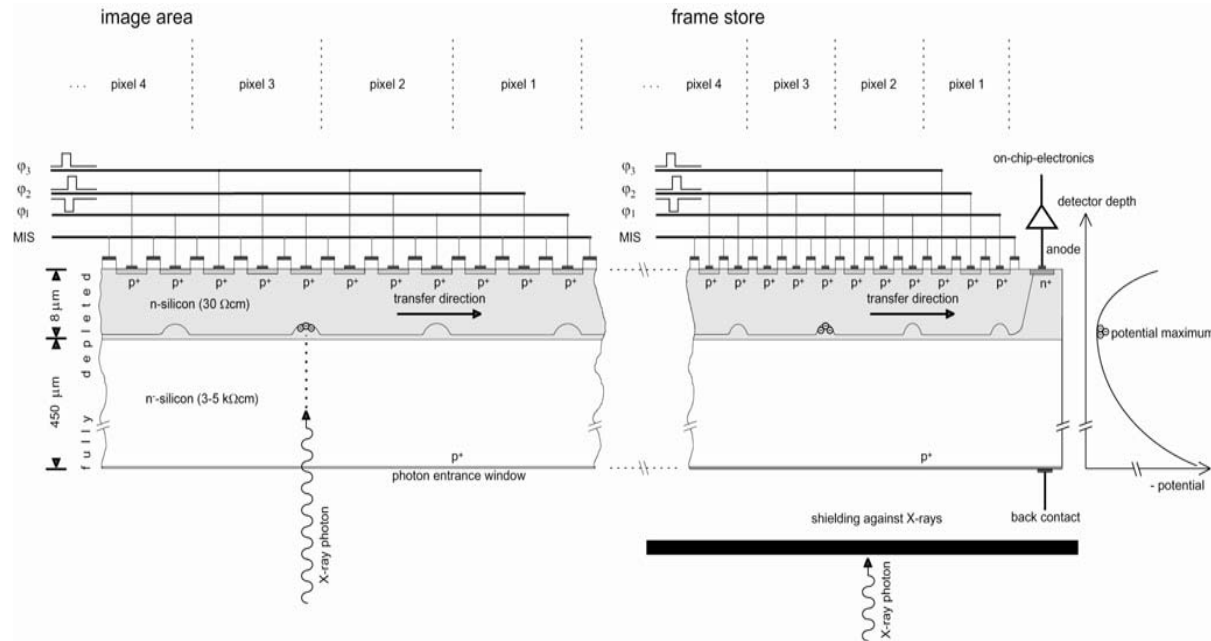
Frame store PN-CCD (DUO/ROSITA)

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Fast transfer in
shielded storage
area for readout

DUO flight model
detectors produced

DUO mission
scheduled for 2007



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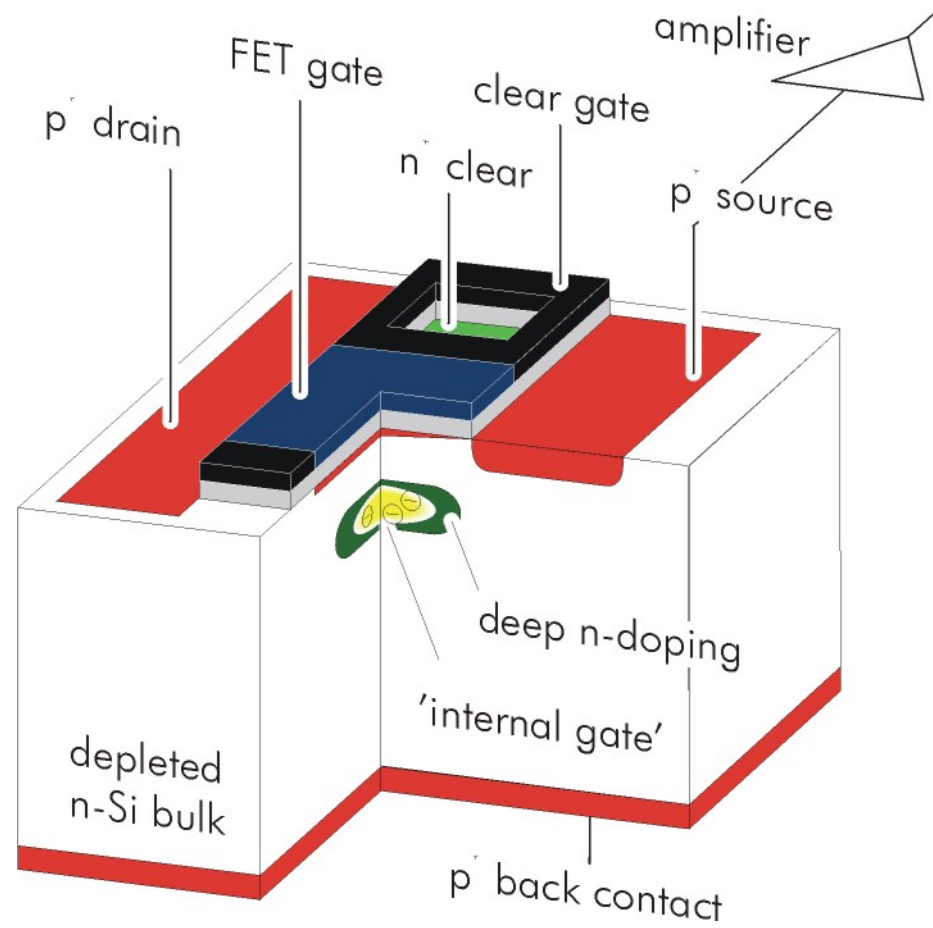


DEPFET Pixel Detectors

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DEPFET: MOSFET Transistor
on depleted silicon bulk
Complete charge collection
and storage
Current readout
Random access of pixels
Fast readout
Low power consumption

Scalable design:
Variable pixel size for
applications in spectroscopy
and tracking

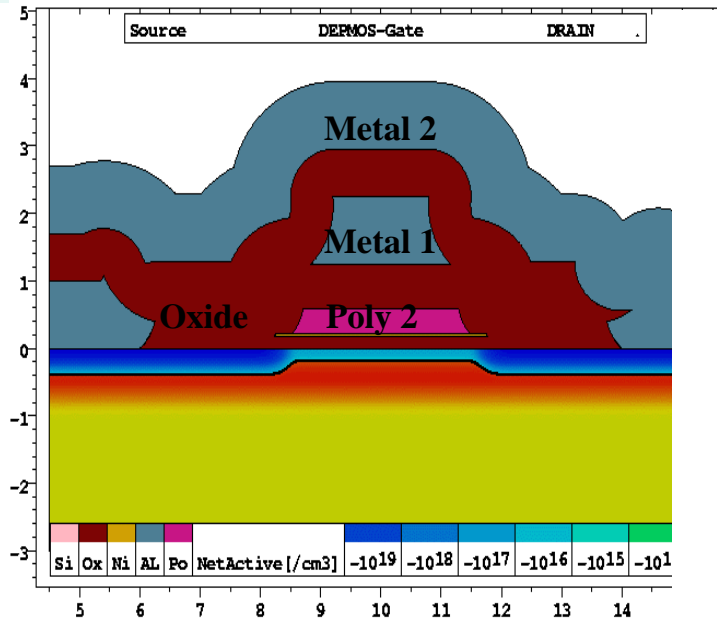




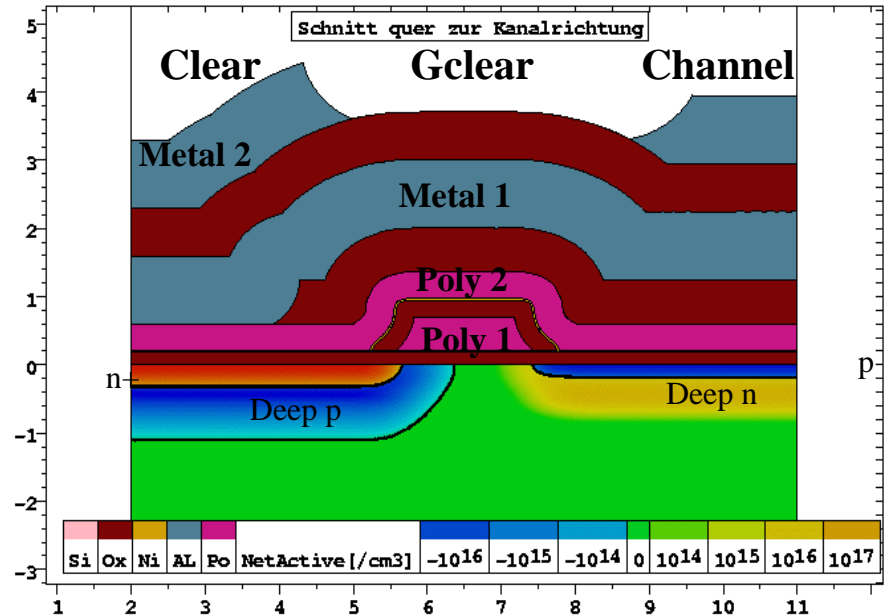
DEPMOS Technology

Double poly / double aluminum process
on high ohmic 150mm wafer

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Along the channel



Perpendicular to the channel
(Clear region)

Double metal necessary for matrix operation

Self-aligned implantations with respect to polysilicon electrodes => reproducible potential distributions over large matrix areas

Low leakage current level: < 200pA/cm² (fully depleted – 450µm)



DEPFET Operation: Energy Resolution

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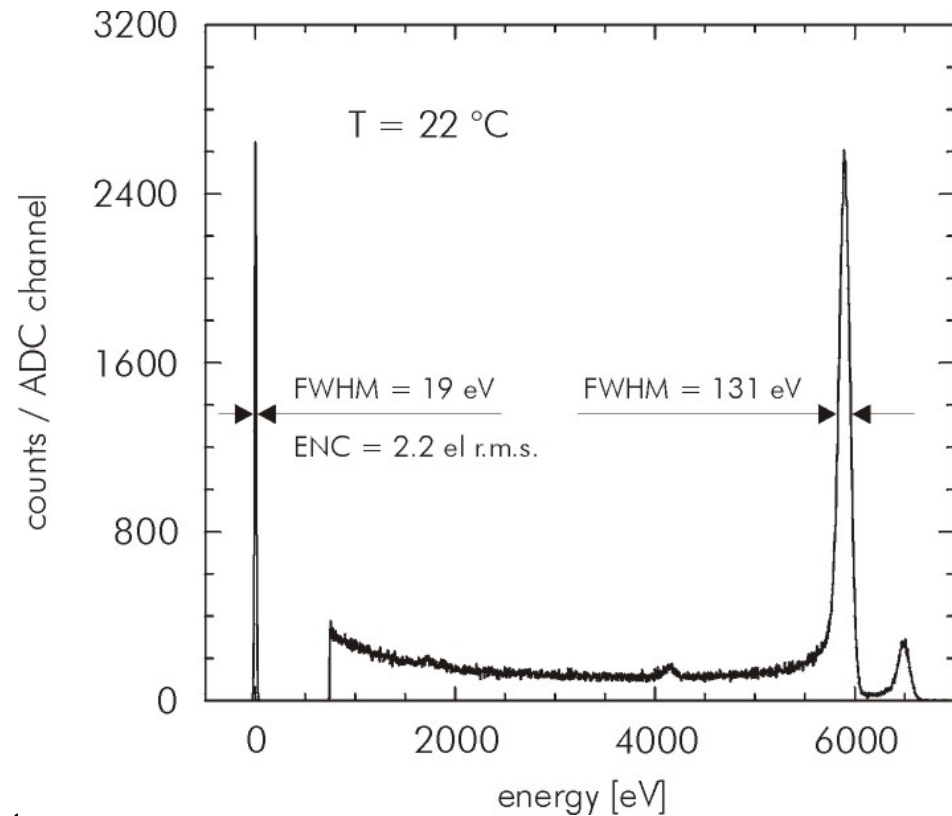
**Excellent energy
resolution
already at room
temperature**

**(measured with a
single DEPFET)**

Setup:

- source follower read out
- commercial pre-amp
- shaping time 6 μ s

"best case conditions"



Best result at Room Temperature:

- 131 eV @ 5.9 keV
- 2.2 el. r.m.s.



Many Design Variations and Applications

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Mini-Pixel

Rectangular
DEPFET structure:

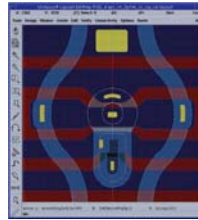
D1 D2
Gate 1

Gate 2

High position resolution
ILC cell size: $25 \times 25 \mu\text{m}^2$
Double readout speed by
Parallel readout

Midi-Pixel

Circular DEPFET structure

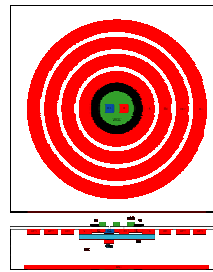


High energy resolution,
medium position resolution

XEUS wide field imager
cell size: $100 \times 100 \mu\text{m}^2$

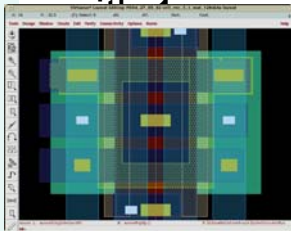
Maxi-Pixel

Integration of a DEPFET
into a drift detector
with 4 drift rings



High energy resolution,
coarse position resolution

SIMBOL-X, ECLAIR
cell size: $\sim \text{cm}^2$

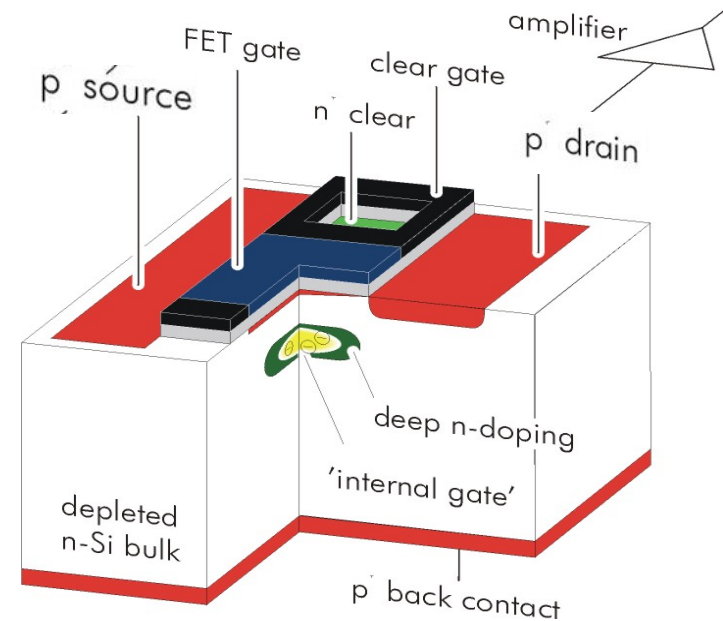
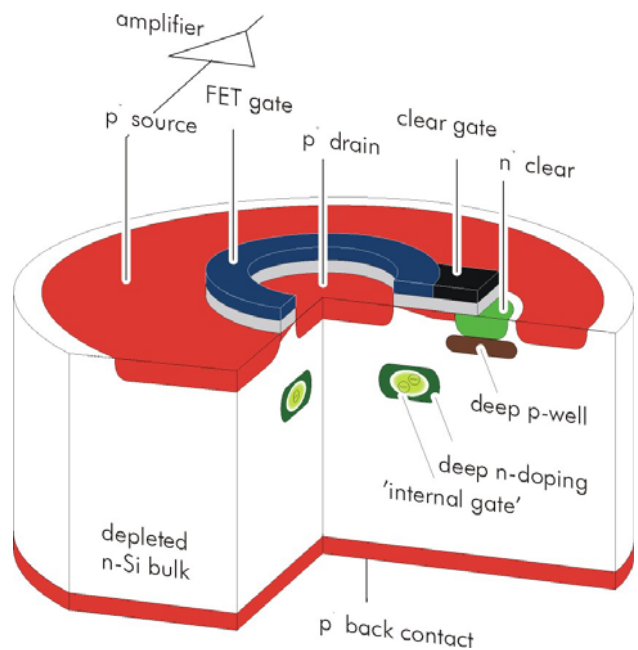


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PXD4 - DEPFET: Two projects on one wafer



| | <i>XEUS (N14-6)</i> | <i>ILC</i> |
|----------------------|-----------------------------|---|
| purpose | imaging spectroscopy | particle tracking |
| sensor size | 7.68 x 7.68 cm ² | 1.3 x 10 cm ² , 2.2 x 12.5 cm ² |
| pixel size | 75 μm | 25 μm |
| sensor thickness | 300 ... 500 μm | 50 μm |
| noise | 4 el. ENC | ~ 100 el. ENC |
| Readout time per row | 2.5 μs | 20 ns |

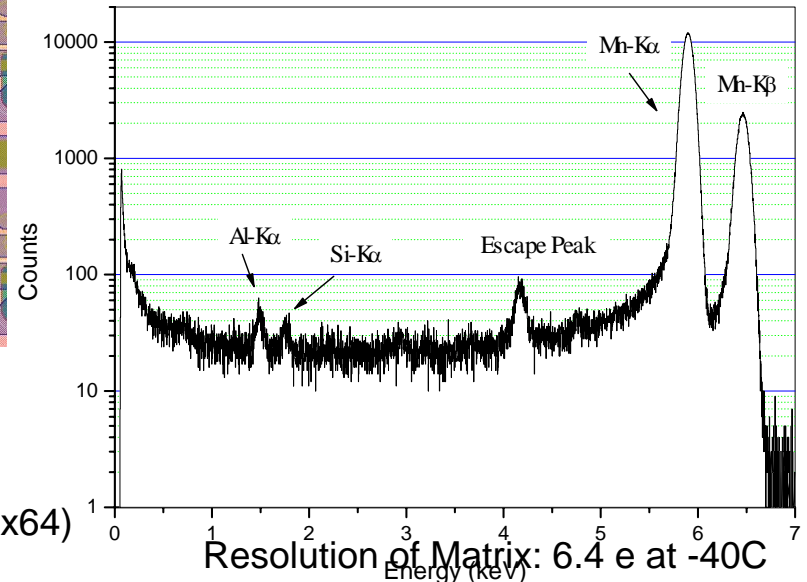
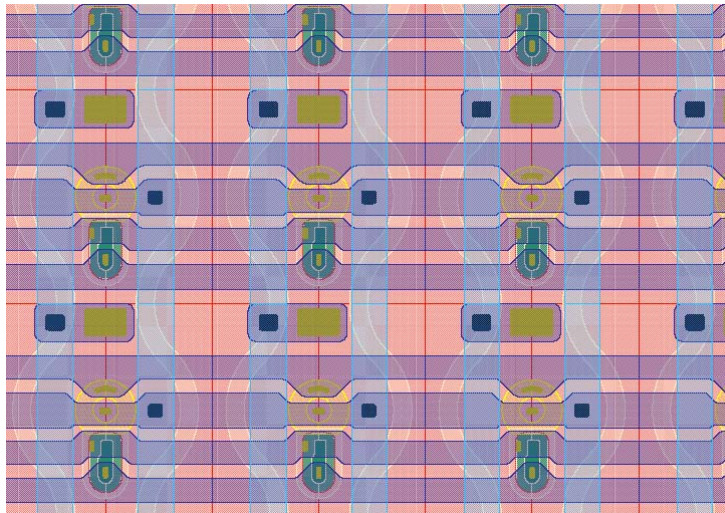
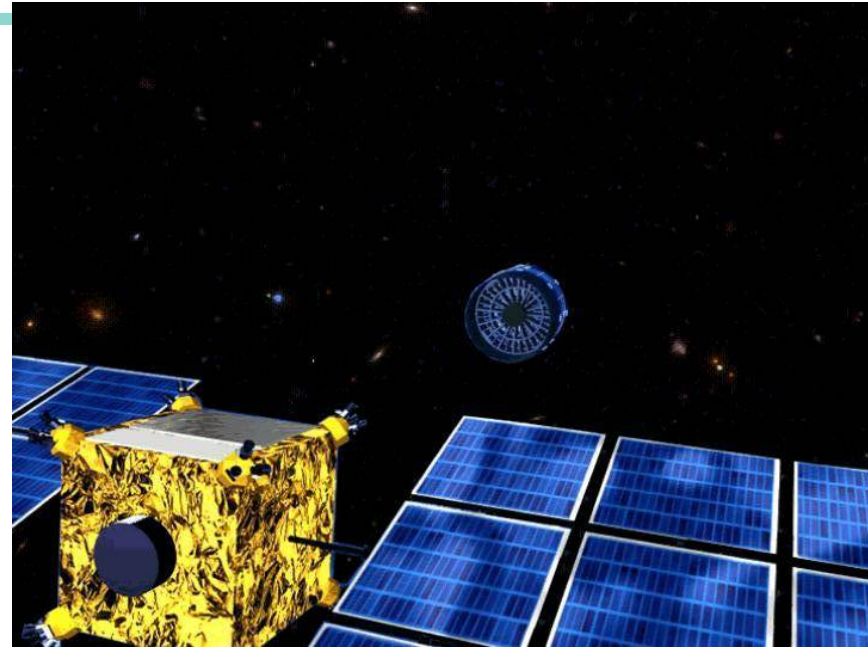


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Application: XEUS WFI

Mission concept:

- X-ray telescope consisting of two satellites, mirror (MSC) and detector (DSC) spacecraft
- Formation flight; active control of focal length with 1 mm³ accuracy



Prototype Matrix with 75 μ m x 75 μ m pixels (64x64)

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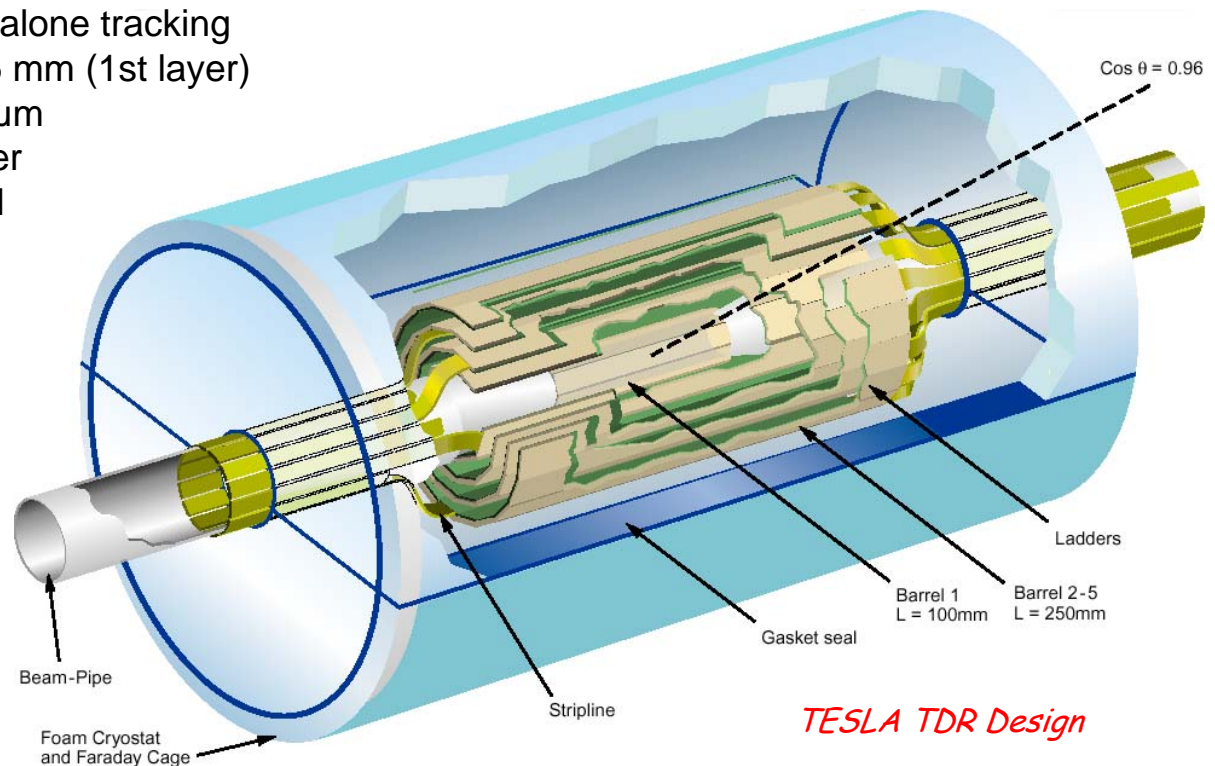


Vertex Detector for TESLA

sensitive area 1st layer module: **100x13 mm²**, 2nd-5th layer : **125x22 mm²** → $\sum 120$ modules

TESLA TDR:

- 5 barrels – stand alone tracking
- close to IP, $r = 15$ mm (1st layer)
- pixel size: 20-30 μm
- $\sim 0.1\%$ X_0 per layer
- overall: ~ 1 GPixel



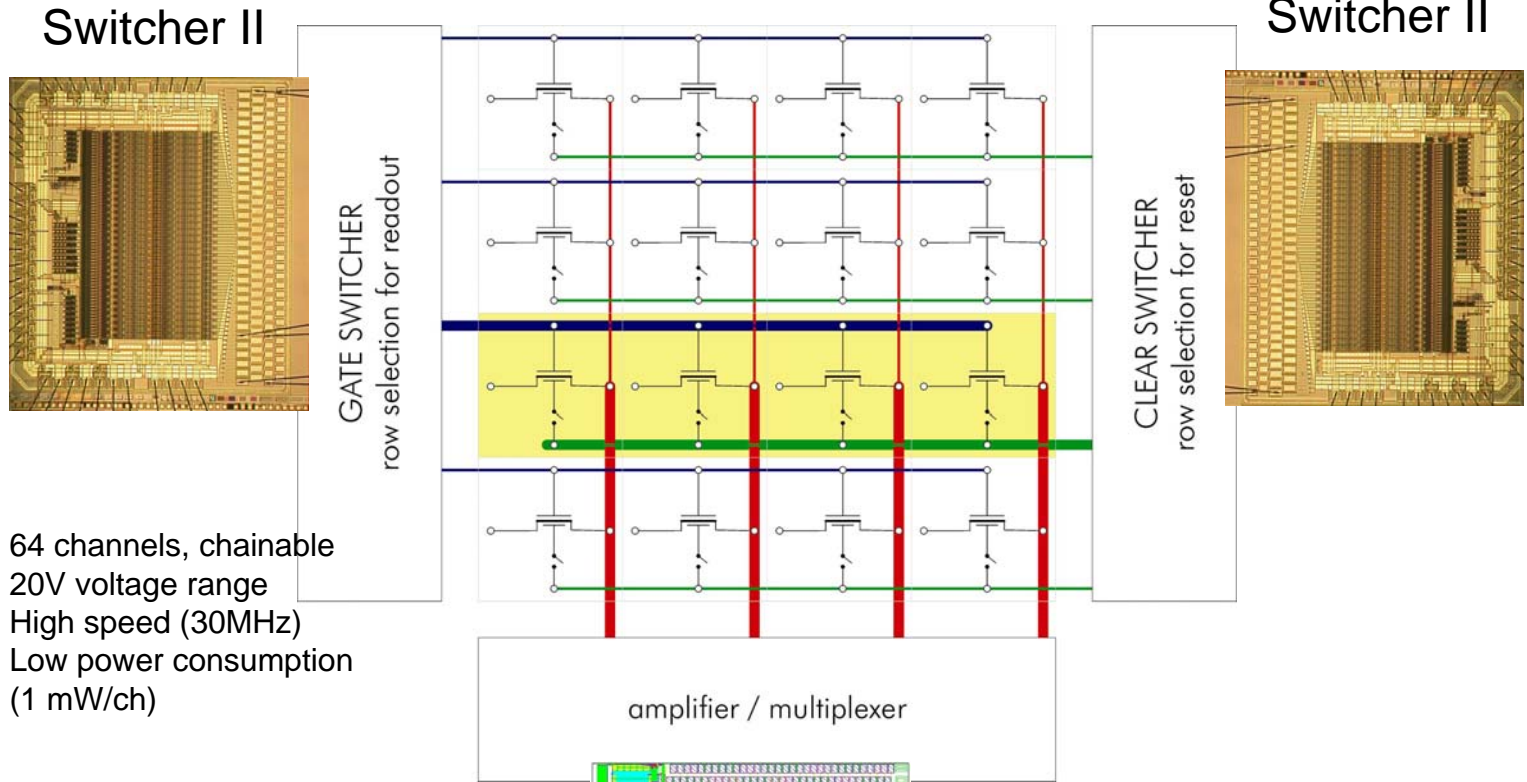
TESLA TDR Design



DEPFET Matrix Operation

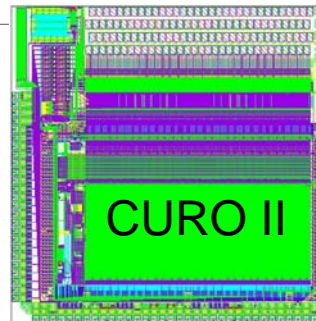
ASICs developed by Universities Bonn and Mannheim

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64 channels, chainable
20V voltage range
High speed (30MHz)
Low power consumption
(1 mW/ch)

128 channels Current readout
Correlated double sampling
(before/after clear: pedestal
suppression)
Hit identification, 0-suppression



Test setup exits and
working
Testbeam scheduled
January 2005

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Test with Sr90 Source

First results with source test (Sr90):

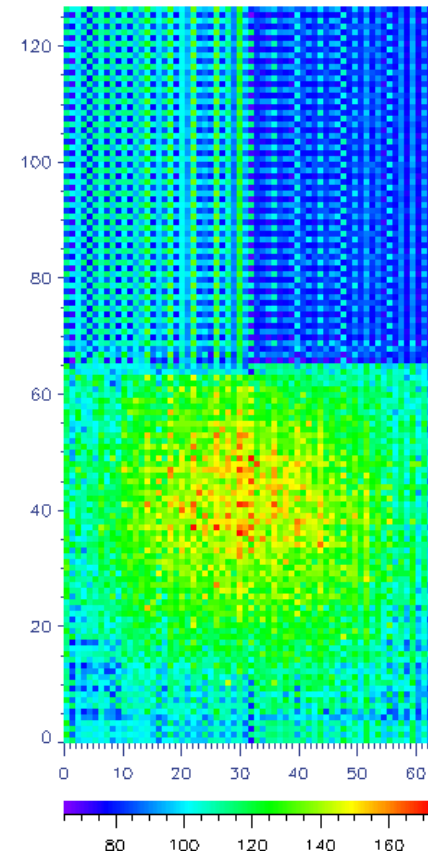
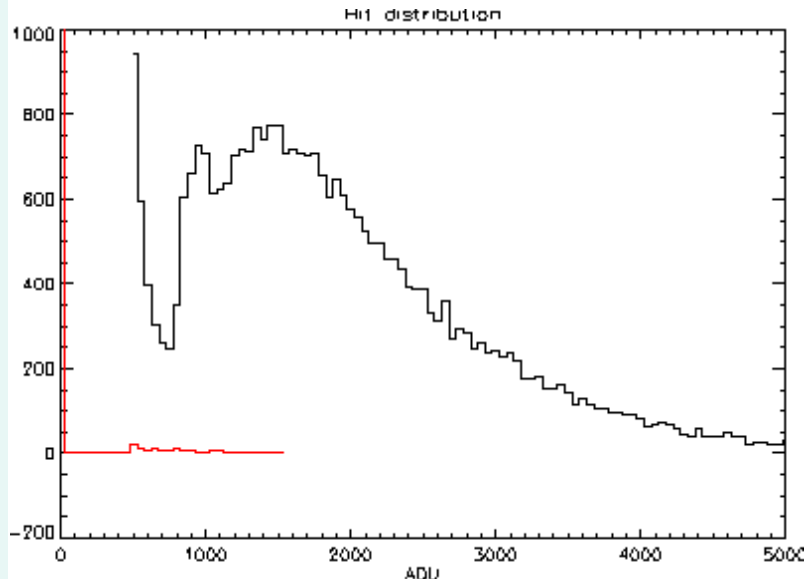
Noise ~80 ADC counts
(not yet optimized, 30 achieved with
different amplifier)

Most likely signal size: 1500 counts

Noise still dominated by hybrid
layout problems.
Ok for testbeam (January)

Hitmap

Region without detector
Region with DEPFET



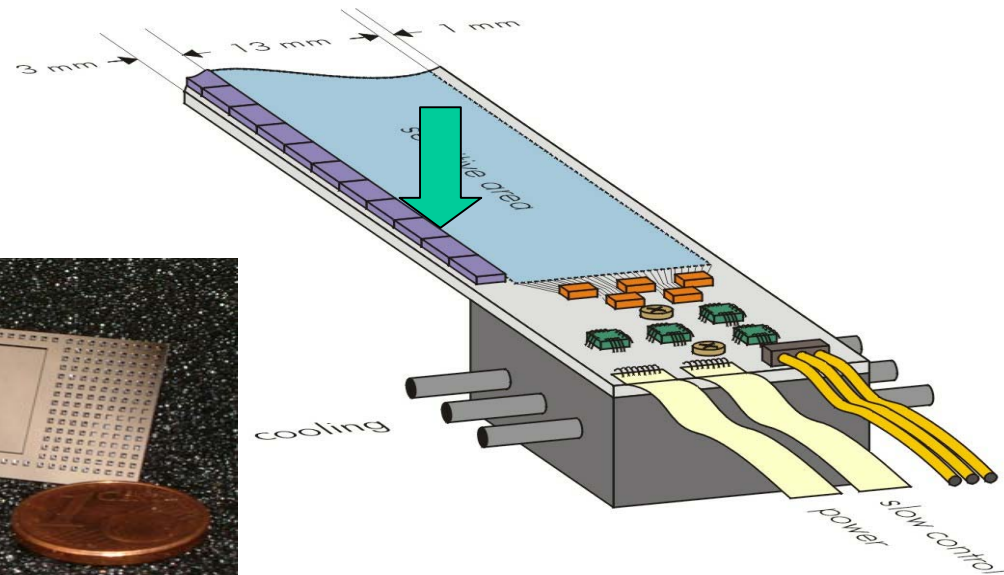
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ILC Vertex Detector: Module Concept & Material Budget

Sensitive area thinned to 50 μm , supported by 300 μm Si-frame

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Estimated Material Budget (1st layer):

Pixel area: 100x13 mm², 50 μm : 0.05% X_0
steer. chips: 100x2 mm², 50 μm : 0.008% X_0
(massive) Frame :100x4 mm², 300 μm : 0.09% X_0

perforated frame: 0.05 % X_0

total: 0.11 % X_0



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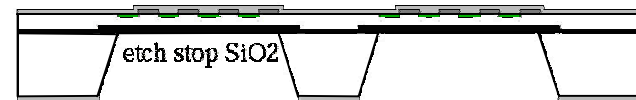
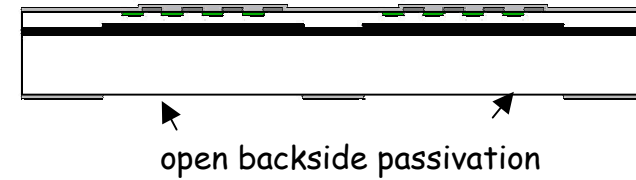
Processing thin detectors

a) oxidation and back side implant
of top wafer

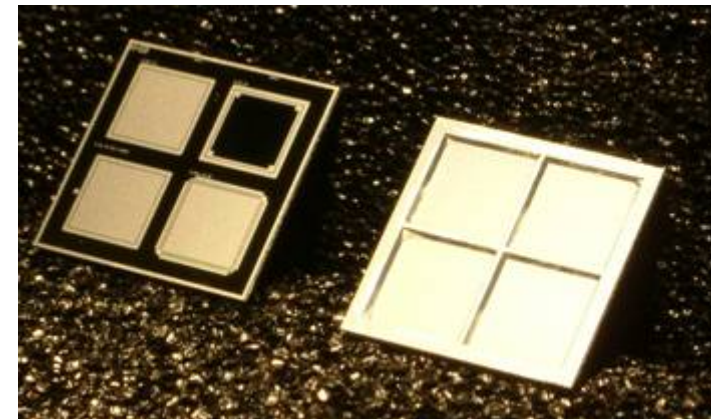
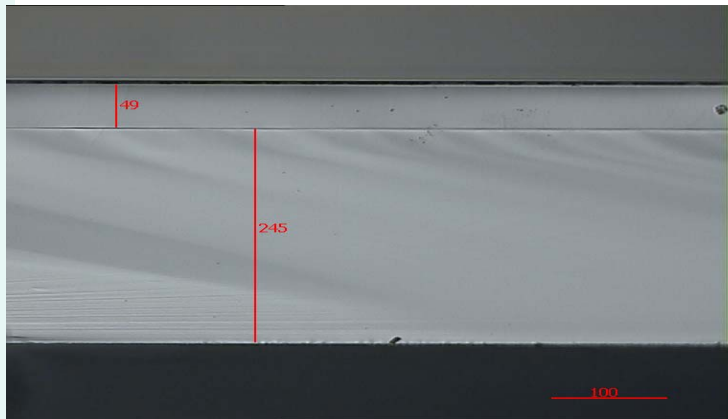


b) wafer bonding and
grinding/polishing of top wafer

c) process → passivation



d) anisotropic deep etching opens
"windows" in handle wafer

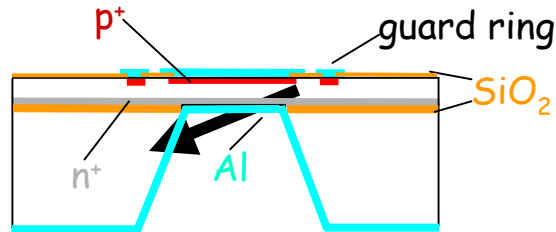




PiN Diodes on thin Silicon

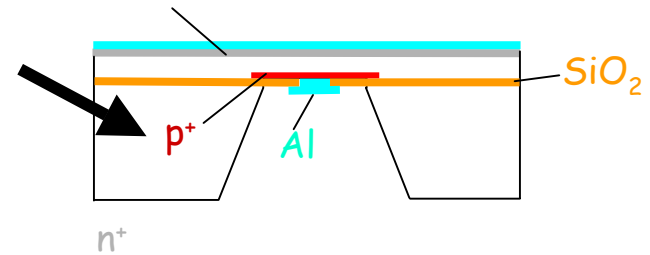
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Type I: Simplified standard technology



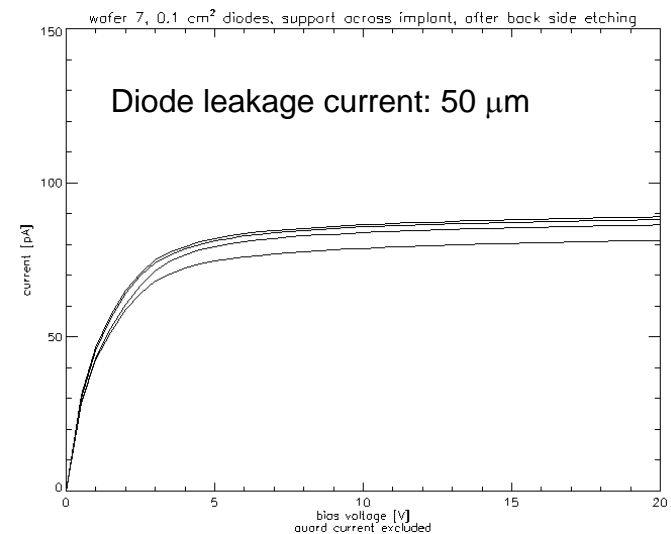
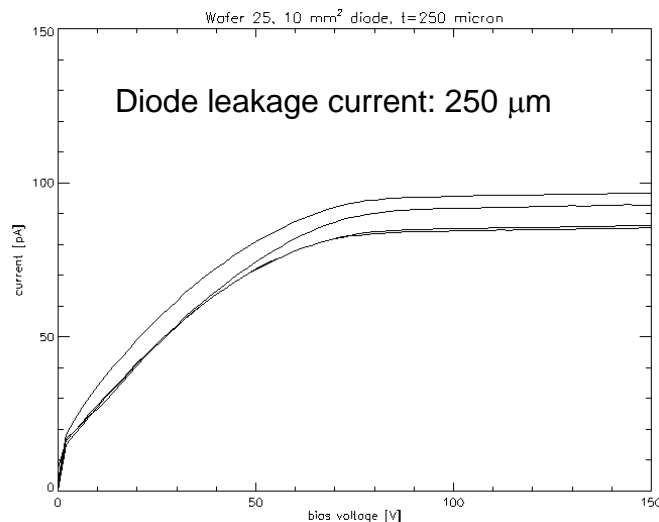
structured p+ on top
unstructured n+ in bond region
10 mm² diodes

Type II: Implants like DEPFET config.



unstructured n+ on top
structured p+ in bond region
0.09 cm² .. 6.5 cm² diodes

- Wafer Bonding: MPI for Microstructure Physics, Halle, (U. Gösele, M. Reiche)
- Top Wafer grinding and polishing: Sico Wafer GmbH, Jena
- Processing and deep etching: HLL



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DEPFET & Competitors for ILC

| | Resolution 5(+) $10/p$ $\sin^{3/2}\theta$ μm | Material budget $\leq 0.1\% X_0/l.$ | Read out Speed (50 MHz) | Power consumpt. | Radiation tolerance Ionisation, n | Remarks |
|---|---|---|-------------------------------|--------------------|---|------------------|
| CCD | 4.2(+) $4.0/p$ $\sin^{3/2}\theta$ μm + + | + R&D | O? R&D !! | ? | +? R&D | Like in SLD |
| HAPS Hybrid APS | $7\mu\text{m}$ - | - - | + + | - - | + + | Like in ATLAS |
| MAPS Monolithic APS CMOS Microelectr. | $2\mu\text{m}$ +++ But at 50MHz ? | + R&D | ? R&D !! | + ? | +? R&D | |
| DEPFET | Like CCD + + | + R&D | +? R&D | + + | +? R&D | |



Advantages of DEPFET Arrays at ILC

1. Charge generation and first amplification in a fully depleted pixel cell:

→ good Signal/Noise

2. No charge transfer needed:

→ better rad. hardness for hadronic irradiation

→ fast read out

3. Wafer scale arrays possible, no stitching of reticles(chips) needed:

→ easier module construction, less material

4. Only one row at a time active, read out at the ladder end:

→ low power consumption, less material

5. Radiation Hardness ??

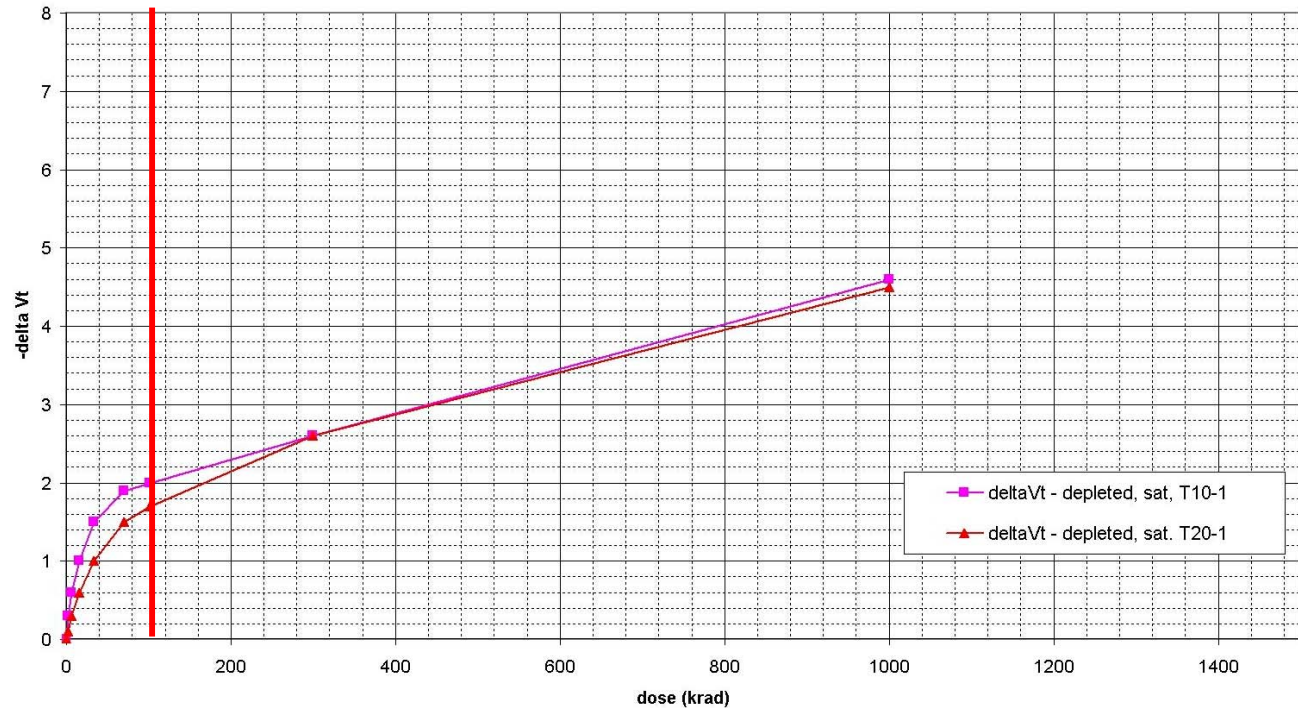
→ to be demonstrated



Radiation Hardness

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-deltaVt vs dose after annealing
18...24 h for each meas. point



Gate voltage shift after irradiation

ILC expectation: 100krad in 5 years

~ 2V shift: to be compared to ~20V gate/clear voltage: looks promising!



Development of Silicon Photomultipliers

Photon Detectors developed at HLL so far:

- **Single X-ray detection: many electrons/photon**
- **Measure energy, position and time of arrival**
- **For optical photons only flux measurements are possible**

New experiments require **single optical photon detection**
with **high quantum efficiency**:

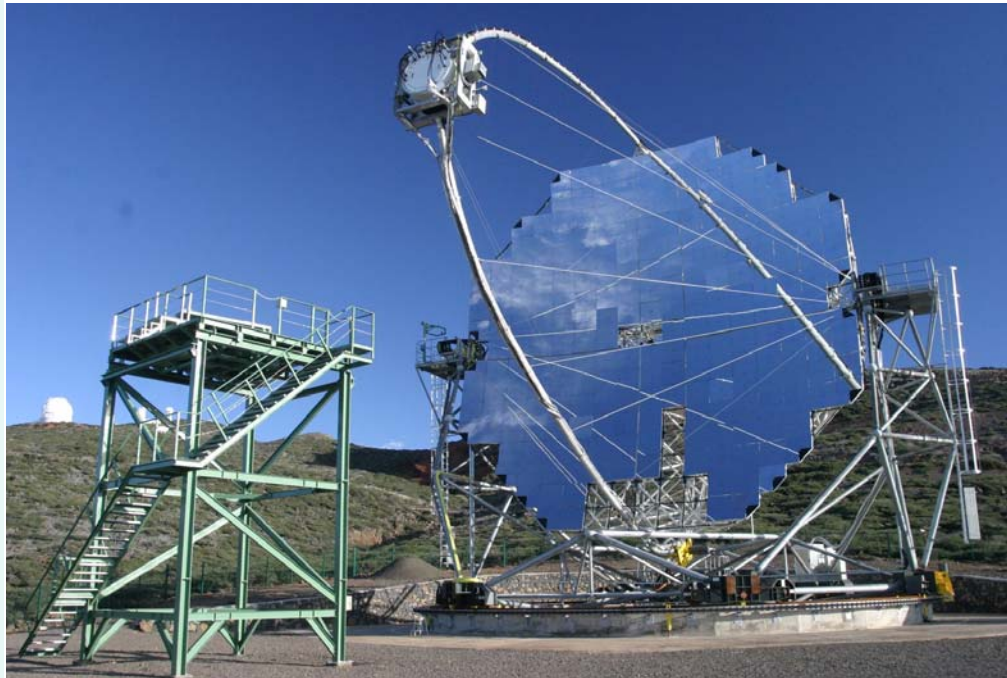
- **EUSO (Extreme Universe Space Observatory)**
- **MAGIC (Major Atmospheric Gamma Imaging Cherenkov Telescope)**
- **High Time Resolution Astronomy**

A new concept promises to fulfill these requirements



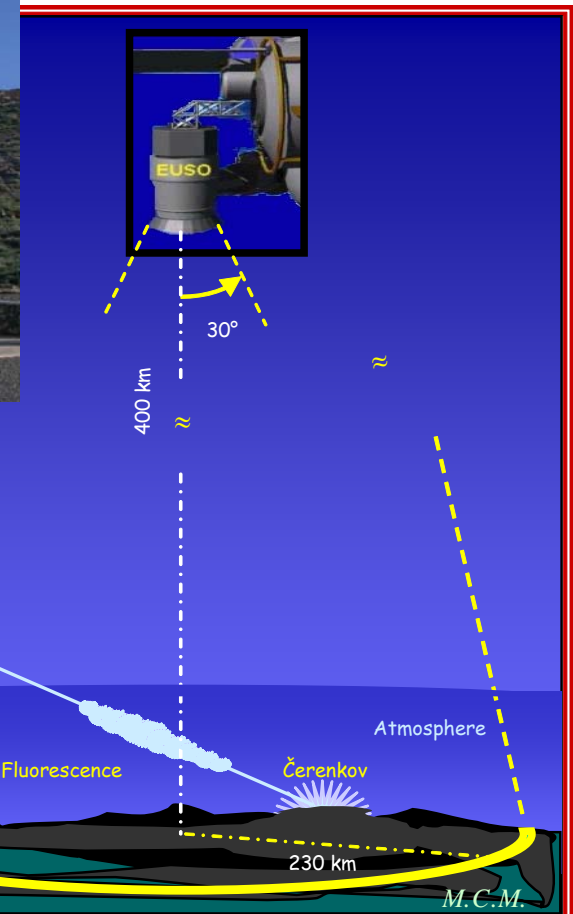
Applications: MAGIC & EUSO

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Presently limited by low QE of
conventional photomultiplier
tubes

Critical: time resolution
(< 2.5 ns MAGIC)





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Development of Silicon Photomultipliers

SiPMs based on avalanche diode arrays (Geiger Mode) already exist (Dogolshein et al.)

However, the QE is still limited (~40%) (Front illumination)

By combining an avalanche structure with a silicon drift diode some shortcomings of existing Silicon Photomultipliers can be overcome:

- **High Quantum Efficiency due to backside illumination (100% fill factor).**
- **High Sensitivity at short wavelengths due to avalanche trigger by electrons instead of holes.**
- **Large area devices with low area and low capacitance multiplication region.**
- **Good time resolution due to field shaping of drift region.**



SiPM concept

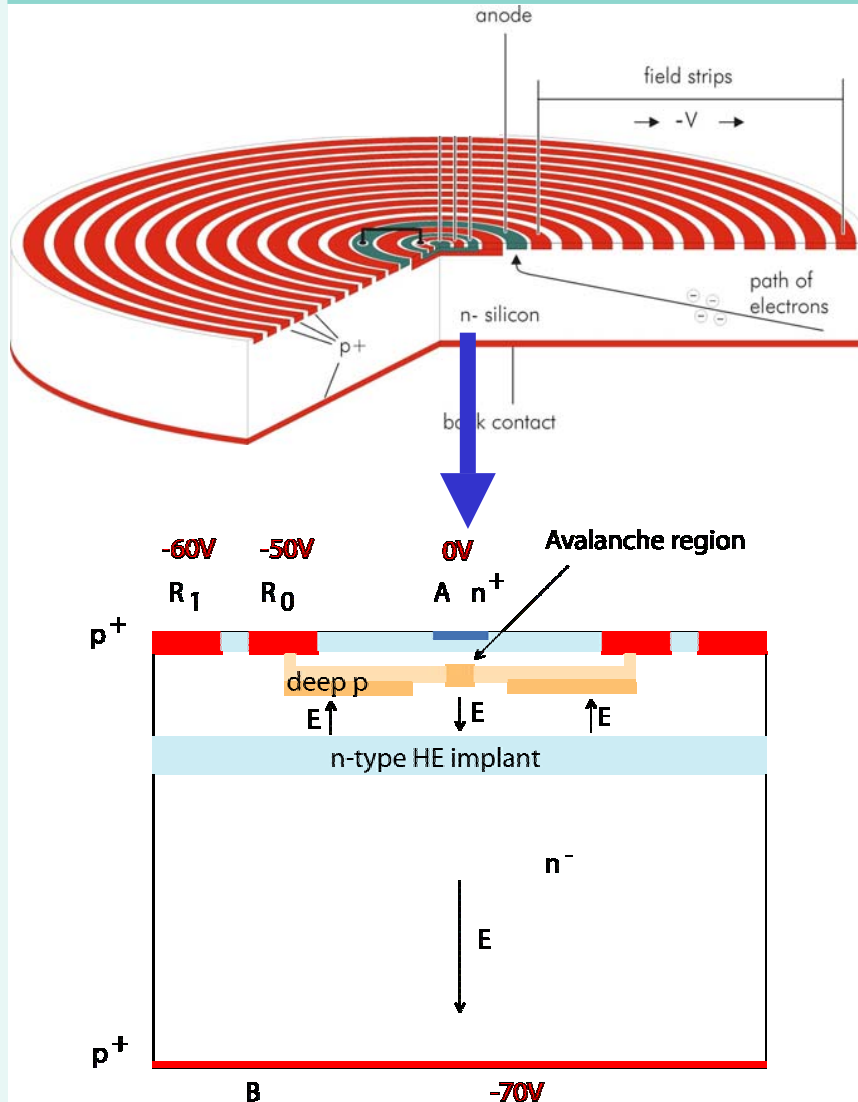


Fig. 1. Concept of the avalanche drift diode

Photons enter through unstructured backside and convert in electron hole pairs.

Electrons drift in the electric field generated by the drift rings to the center.

The deep p implant generates a high field region in which the avalanche multiplication occurs.

The low capacitance of the small avalanche region gives detectable signals at small gain, thus reducing cross talk (due to photon emission)



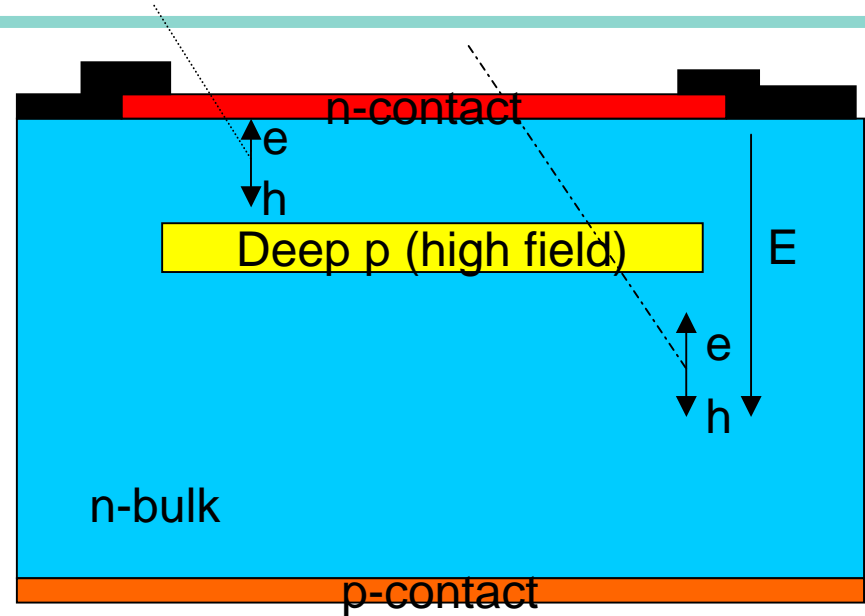
Advantages of backside illumination

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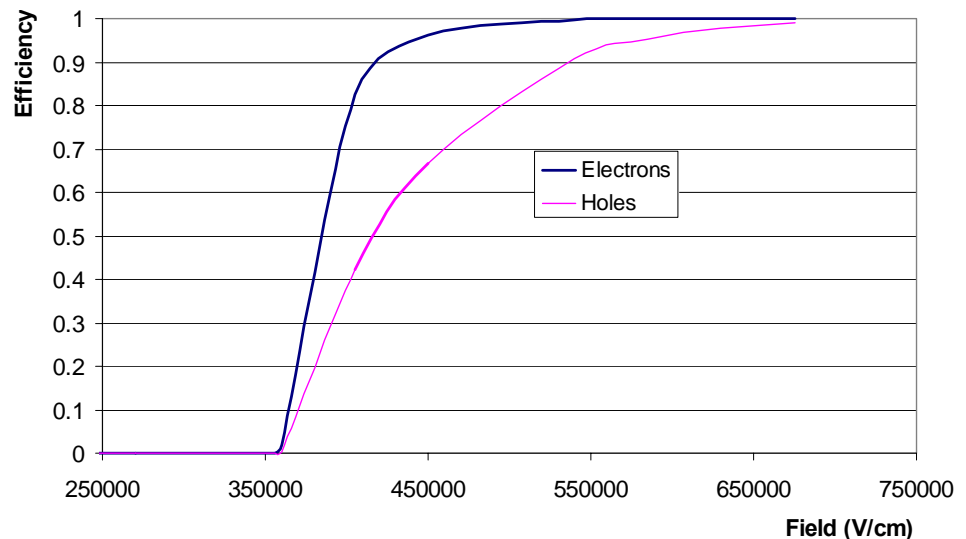
Frontside illumination:

QE limited due to:

- Surface structures
- Short wavelength photons convert close to the surface, before the HF region. Thus only holes can trigger an avalanche, with reduced efficiency



Avalanche Efficiency (1 μm high field region)

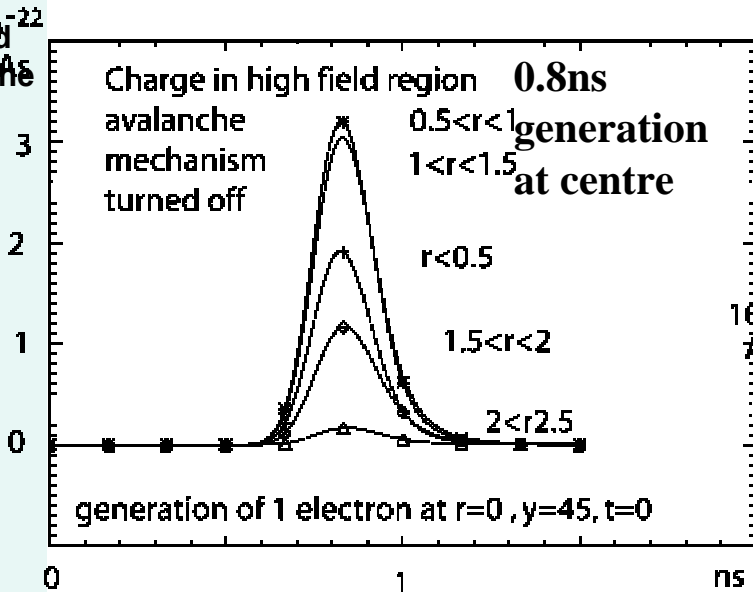




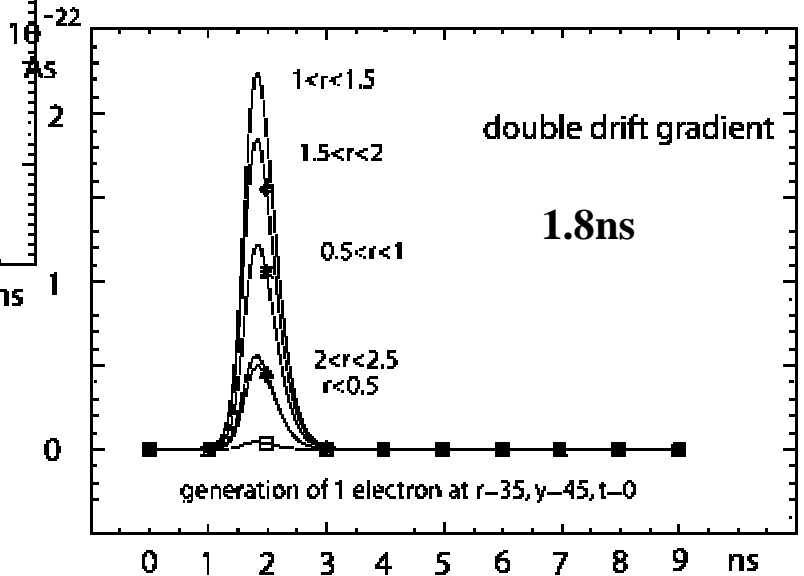
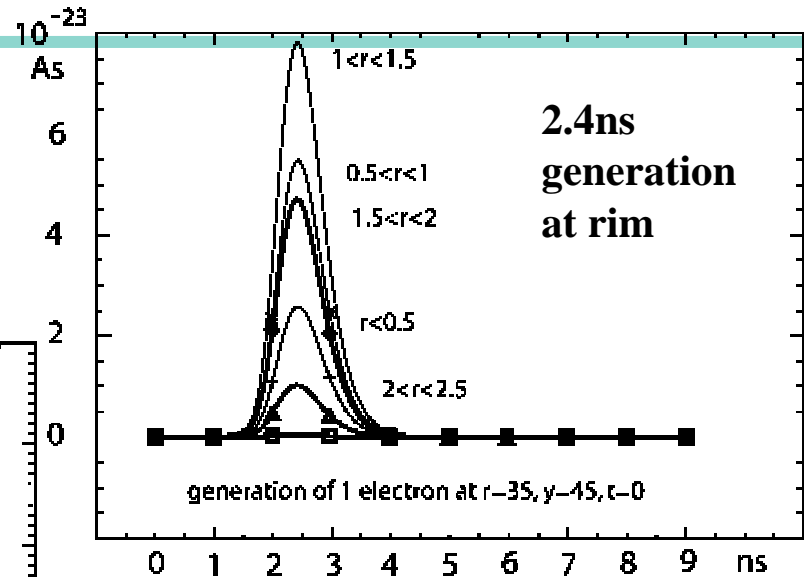
Avalanche drift diode – charge focusing

- » Does all charge focus into homogeneous high field region?
- » Turn avalanche mechanism off
- » Charge density in high field region at different radial regions

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Charge collection time 0.9ns
for generation in centre
All charge within $r=2$



All charge within $r=2.5$



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SiPM Development

- » Conceptual Design and Simulations ongoing
- » First test structures to be produced early 2005
- » First functional devices end 2005
- » Complete SiPM arrays in 2006

- » Challenges:
 - » - Dark rate (control bulk generated leakage currents. Thinning!
 - » - Cross talk between pixel due to photons emitted in an avalanche and reabsorbed in neighboring pixels (-> low amplification!)



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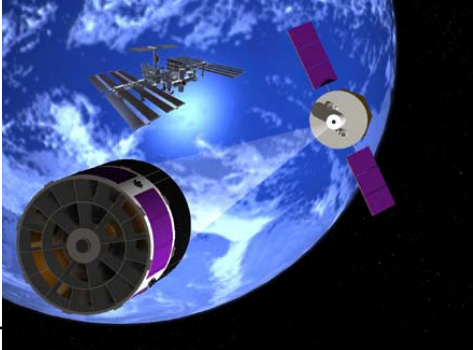
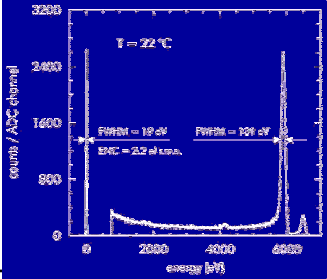
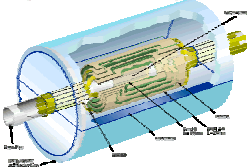
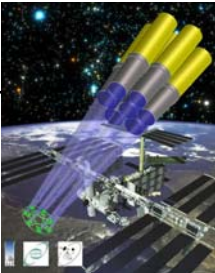
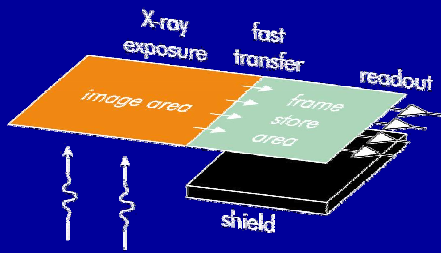
Conclusions

- » New Projects, especially for WHI experiments, are emerging:
 - » - Silicon Drift Detectors for Muon Cooling
 - » - DEPFET Pixel Detectors for ILC
 - » - Silicon Photomultiplier for MAGIC & EUSO
- » These projects make use of the production facilities of the HLL, unlike ATLAS SCT, which used mainly design and test facilities
- » Remark: The DEPFET project urgently needs support by a strong ILC physics group!



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Major Projects

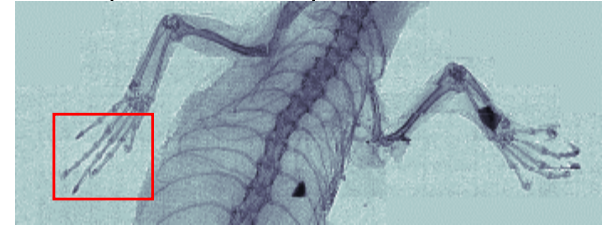
| Project | Institutes | Physics | Device | Status |
|---|--|--|------------------------------------|---|
| XEUS (X-Ray Evolving Universe Spectrometer) | MPE ESA | X-Ray Astronomy (Mirror Telescope)  | Thick DEPFET Pixel Detector | Small size prototype under test  |
| ILC (Tesla)  | WHI Bonn Mannheim | E+ E- linear collider Vertex Detector | Thin DEPFET Pixel Detector | Thick Prototypes under test |
| DUO | MPE NASA | X-Ray Astronomy (Mirror Telescope)  | Frame store pnCCD | Prototype existing Production start |
| Rosita | MPE ESA | Like DUO | Frame store pnCCD |  |



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More Projects....


| | | | | |
|--|--|--|--|---|
| HTRA High Time Resolution Astrophysics | MPE MPIA MPA | Observation of rapidly varying objects (Ground based Optical Telescope) | pnCCD | Produced together with DUO |
| Sensors for adaptive optics | MPE ESO | Rapid corrections for change in the atmosphere | pnCCD | Produced together with DUO |
| Compton Camera | MPE Siegen Essen Bonn Jülich Milano | Medical imaging, pharmaceutical investigations | Controlled Drift Detector | Produced together with DUO |
| SIDDHARTA | MPE Frascati Wien | Investigation of kaonic atoms (X-Ray Spectroscopy) | Drift detectors ~200 of 1cm² | Start July 2004 |





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More Projects.... (not complete)

| | | | | |
|---|---------------|--|--|-------------------------------------|
| Muon collider | WHI | Muon Cooling By friction (De/dx) | Silicon drift detector (simila to Siddahrta) | Samples for test setup delivered |
| DRAGO | MPE Milano | Medical imaging | Multicell Silicon drift detector | Available |
| FELIX | MPE Milano | X-ray fluorescence (art) | Drift detectors  | Available |
| X- and Gamma ray imaging spectroscopy | MPE | Gamma and high energy X-ray detection | Drift detectors | Available |
| MAGIC (EUSO) | WHI | Air shower telescope | Si- Photomultiplier (avalanche) | Design phase |

